

TEST REPORT

Sample Name : Printed Circuit Board

Sample Model : See " Sample Detail Information"

Applicant Name : HUADING GROUP CO., LIMITED

Test Type : Entrust test

Jiangsu LABone Testing Services Technology Co., Ltd.



TEST REPORT

Report No.: CJ2112013M02EA Report Date: 2021/12/28 Page: 1 of 5

Applicant Name : HUADING GROUP CO., LIMITED
Applicant Address : UNIT D,WORLD TRADE CENTRE, NO.122 SHUGUANG ROAD, HANGZHOU CITY , ZHEJIANG PROVINCE, THE PEOPLE'S REPUBLIC OF CHINA

The following samples are submitted and identified on behalf of the applicant as:

Sample Description :

Sample Name : Printed Circuit Board
Sample Model : See next page " Sample Detail Information"
Sample Quantity : 2 pcs
Sample No. : A-1、 B-1
Applicant No. : /
Manufacturer : /
Receiving Date : 2021/12/02
Test Period : 2021/12/03~2021/12/07

Test Conducted:

As requested by the applicant, for details refer to attached page(s).

Approved by  Reviewed by

Sean Zhu

Tested by

Wen zhuming

Sean Zhu, Technology Director

Declaration: This report is invalid without "Special Seal for Testing" of LABone. The test data and results in the report only serve for the submitted test samples. LABone is not responsible for the test data and results provided by the applicant. Any change, modification or partial reproduction of this report is invalid. The test data and results issued in this report are only for the use of the entrusting party. CJ2112013M02E report is invalid and replaced CJ2112013M02EA.

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Conclusion:

Section No.	Test Name	Evaluation
M01	Surface copper, hole copper (position 1)	Conforming

Lab Environmental Condition:

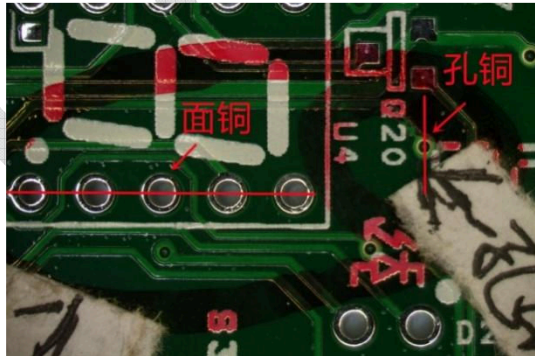
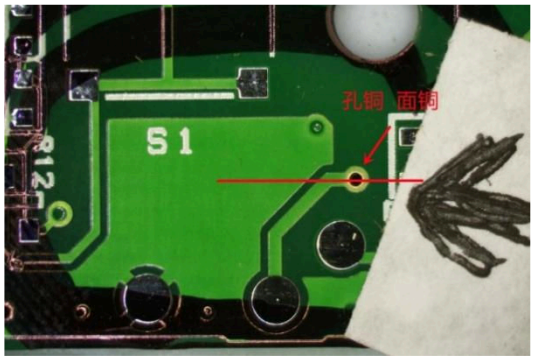
Ambient Temperature	(23±2) °C	Relative Humidity	(50±5)% RH
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Sample Detail Information:

Sample No.	A-1	B-1
Contract No	HDC2109304	HDC2108301
Model	01771265-09-J	01771285-04-D
PO	45174649 10	45173588 10
Anniversary	4221	3621

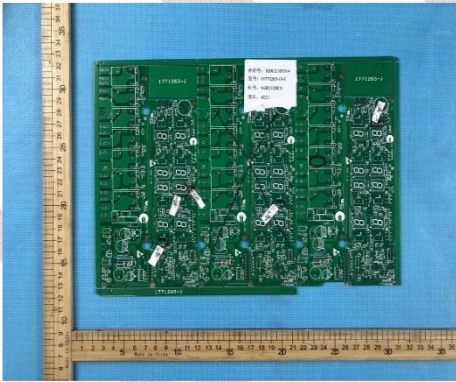
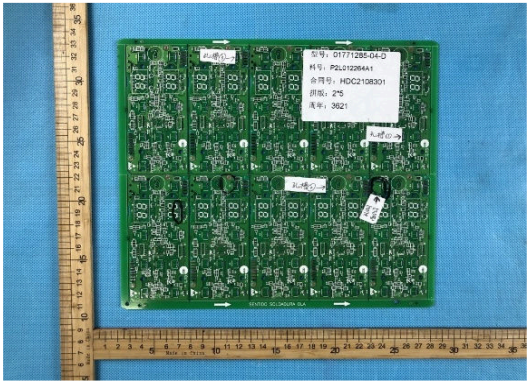
Test Items, Method and Results:

M01. Surface copper, hole copper (position 1)

Sample No.	A-1、B-1
Refer Specs	IPC Class II standard
Test Method	<p>Take cross section test at the locations as shown below, then use metallographic microscope to observe and measure specified dimensions.</p> <div style="display: flex; justify-content: space-around;">   </div> <div style="display: flex; justify-content: space-around; margin-top: 5px;"> A-1 B-1 </div>
Acceptance	A-1: Average hole copper ≥ 20 μm, surface copper 70 μm, surface copper ≥ 63.00 μm.

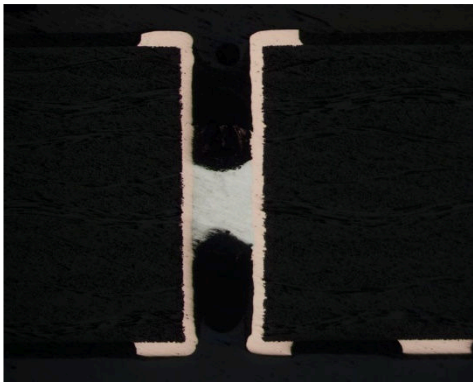
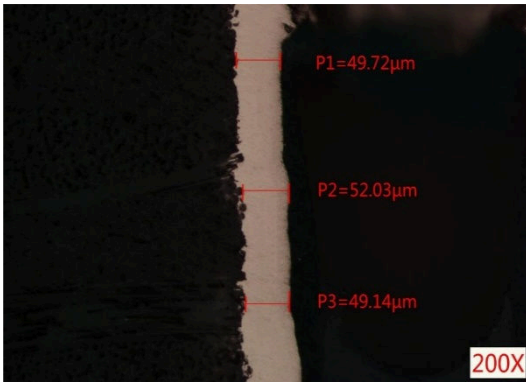
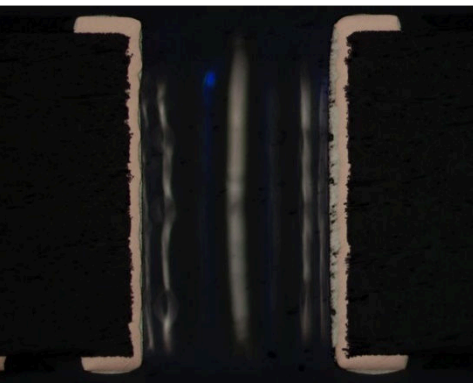
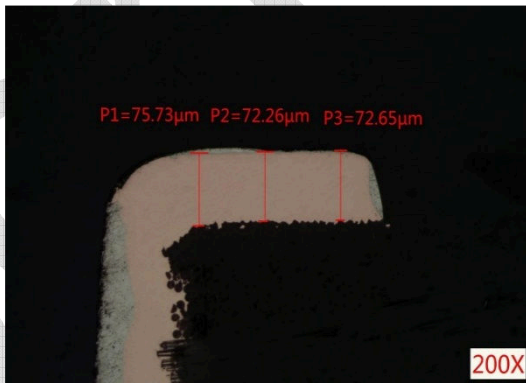
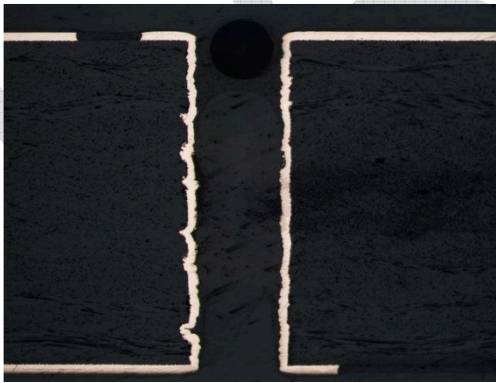
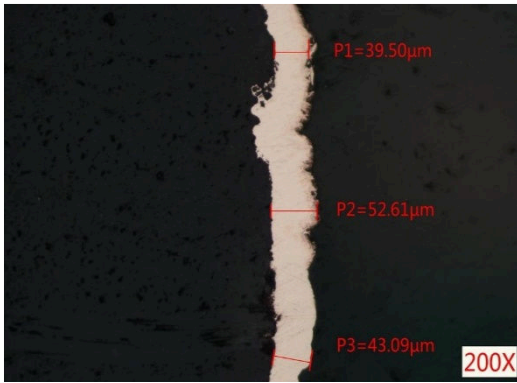
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Criteria	B-1: Average hole copper $\geq 20 \mu\text{m}$, surface copper $35 \mu\text{m}$, surface copper $\geq 35.00 \mu\text{m}$.							
Deviation	/							
Test Results	Sample No.		Test Results (unit: μm)				Evaluation	
			P1	P2	P3	AVG		
	A-1	Hole copper thickness		49.72	52.03	49.14	50.30	Conforming
		Surface copper thickness		75.73	72.26	72.65	73.55	Conforming
	Sample No.		Test Results (unit: μm)				Evaluation	
			P1	P2	P3	AVG		
B-1	Hole copper thickness		39.50	52.61	43.09	45.07	Conforming	
	Surface copper thickness		39.50	41.43	40.47	40.47	Conforming	
Test Instruments	No.	Equipment Name	Equipment Number		Calibration Due Date			
	1	Metallographic microscope	QT-NBSY-47		2021/06/10~2022/06/09			
Remarks	/							
Sample and Test Pictures								
								
Fig.M01.1 Before the test A-1			Fig.M01.2 Before the test B-1					

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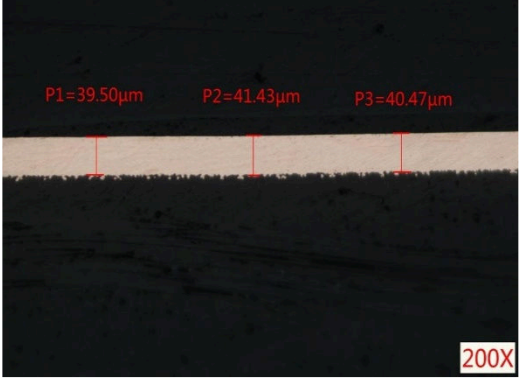
	
<p>Fig.M01.3 The whole Hole copper thickness (A-1)</p>	<p>Fig.M01.4 Hole copper thickness (A-1)</p>
	
<p>Fig.M015 The whole Surface copper thickness (A-1)</p>	<p>Fig.M01.6 Surface copper thickness (A-1)</p>
	
<p>Fig.M01.7 The whole Hole copper thickness (B-1)</p>	<p>Fig.M01.8 Hole copper thickness (B-1)</p>

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Fig.M01.9 Surface copper thickness (B-1)	

End of Report